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(71) Applicant and

(72) Inventor: HERNANDEZ, William [US/US]; 851 W.
Calle Ranunculo, Tucson, AZ 85704 (US).

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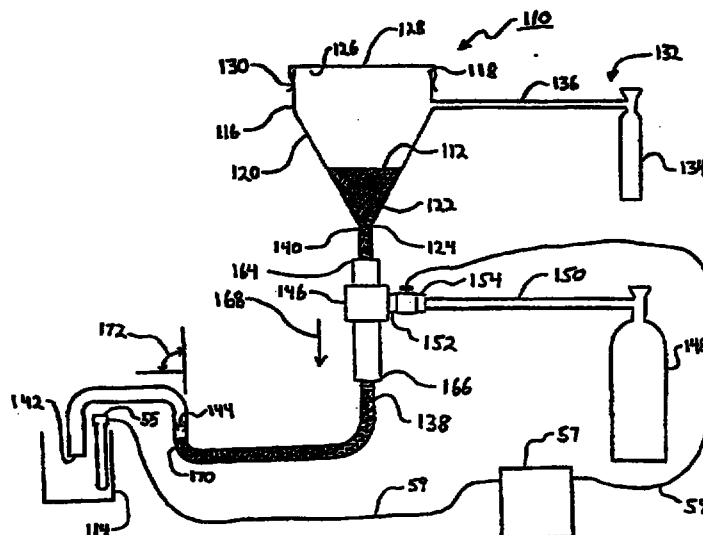
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(74) Agent: SULLIVAN, Stephen, T.; Sullivan Law Group,
Suite 120, 5060 North 40th Street, Phoenix, AZ 85018-
2140 (US).

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(54) Title: APPARATUS AND METHOD FOR SUPPLYING SOLDER BALLS



(57) Abstract: An apparatus (10) is provided for supplying solder balls (12) to a receptacle (14). The apparatus (10) includes a reservoir (16) for storing the solder balls (12) and a flow path (38). The flow path includes a first end (40) connected to and in fluid communication with the reservoir (16) and a second end (42) for supplying the solder balls to the receptacle. The apparatus includes a flow actuator (46) in fluid communication with the flow path (38) to actuate the flow of the solder balls (12) from the reservoir (16) through the flow path (38) to the receptacle (14). A trap is disposed in the flow path (38) for trapping the solder balls (12) and stopping the flow of the solder balls to the receptacle (14) when the flow actuator (46) is not actuated. Related methods are disclosed.

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